

L Number	Hits	Search Text	DB	Time stamp
-	31	((Chip or die) with (bump or ball)) and ((cmp or (chemical near polish)) with (chip or die or encapsulant or encapsulate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:28
-	1	("20020004288").PN.	US-PGPUB	2003/08/26 14:25
-	1	("5989982").PN.	USPAT	2003/08/26 14:25
-	207	(Chip or die) and (cmp or (chemical near polish)) and (encapsulant or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:36
-	143	((Chip or die) and (cmp or (chemical near polish)) and (encapsulant or encapsulate)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:36
-	0	6528894.URPN.	USPAT	2003/08/26 14:32
-	19	("3716907"   "3767394"   "3978578"   "5046161"   "5084752"   "5136364"   "5217597"   "5349240"   "5406122"   "5481135"   "5547906"   "5599749"   "5600180"   "5641113"   "5726501"   "5825078"   "5956605"   "6124633"   "6208025").PN.	USPAT	2003/08/26 14:32
-	7	csp and (cmp or (chemical near polish)) and (encapsulant or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:46
-	14	(csp or (chip adj scale)) and (cmp or (chemical near polish)) and (encapsulant or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:49
-	4	((glass or psuedo) adj wafer) and (cmp grinded or grinding or (chemical near polish)) and (encapsulant or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:57
-	4	((glass or psuedo) adj wafer) and (cmp or grinded or grinding or (chemical near polish)) and (encapsulant or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:58